

A

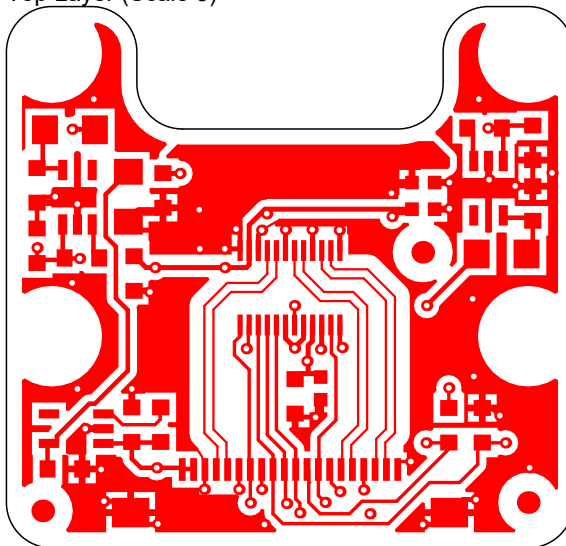
B

C

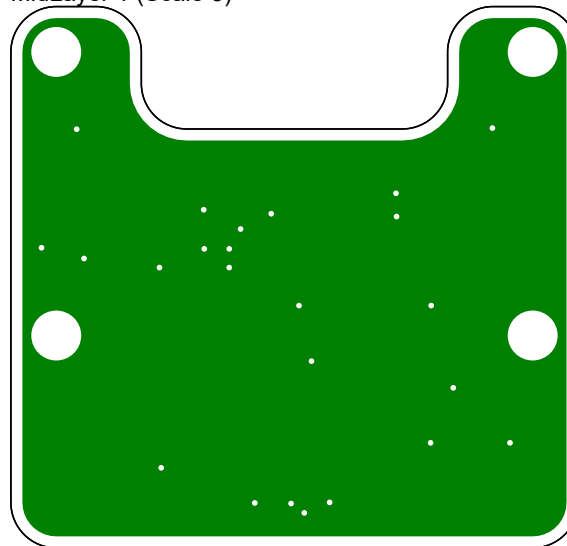
D

E

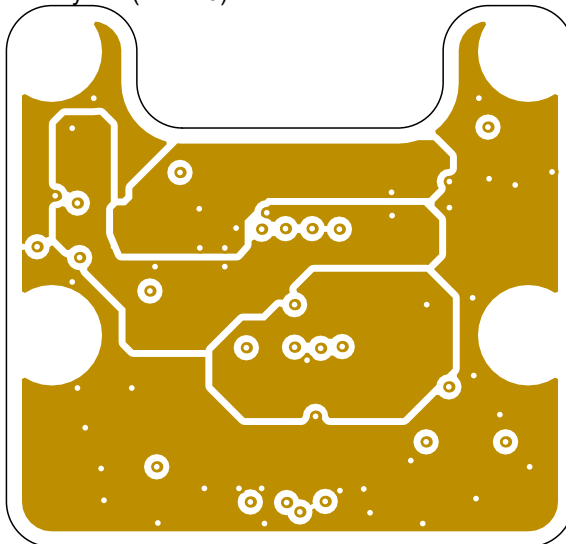
Top Layer (Scale 3)



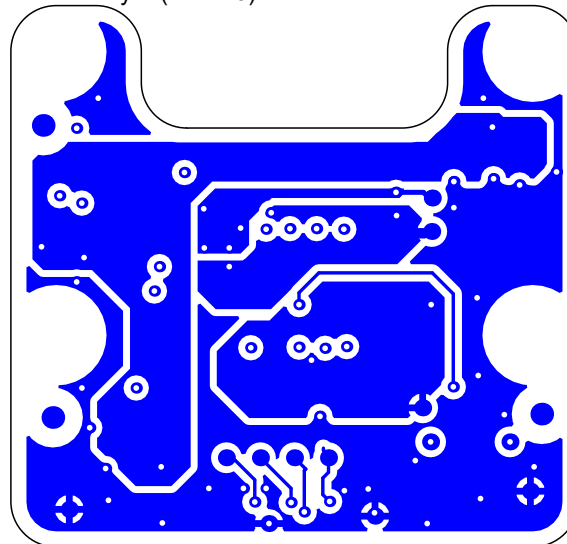
MidLayer 1 (Scale 3)



MidLayer 2 (Scale 3)



Bottom Layer (Scale 3)

**FABRICATION NOTES:**

Fabricate per IPC-6011 & IPC-6012 CLASS 2
Inspect per IPC-A-600 CLASS 2
Test per IPC-TM-650

- * PCB has 4 copper layers
- * Copper thicknesses are finished and include base foil plus Cu plating on plated layers.
- * PCB thickness: 63mil +/- 3mil
- * Min. trace width/clearance: 0.1/0.1mm
- * Min. hole drill/ring: 10mil/20mil
- * Soldermask gang relief is allowed for pads in same footprint, if footprint is NSMD.
- * Silkscreen, non-conductive epoxy ink, color: white
- * Remove silkscreen as needed to prevent ink on any exposed copper
- * Surface finish: ENIG
- * Hole dimensions are finished size, +/-3mil
- * Linear board dimension tolerance: +/-10mil
- * Bow, twist, warp not to exceed 0.75% of greatest diagonal span
- * PCB shall be UL Recognized printed wiring board (ZPMV2), minimum flammability rating 94V-0
- * PCB shall be marked with fabricator company or trade name, UL mark, and date code using legend ink on secondary side
- * All PCBs shall be electrically tested for opens and shorts per gerber. Test marking shall be marked on secondard side.

Fabricator shall panelize the PCB using mouse bites and tab routing. V-scoring not allowed.

Controlled impedance differential pairs shall be within +/-10% for 100ohm targets, and +/-10% for 90ohm targets. See Sheet 3 for transmission line details and location of 90ohm differential pairs.

Title: **BG0250TG**

Number: D0000999

Revision: R0M0
E0

Date: 10/14/2019

Sheet: 1 of 3

Drawn by: Brandon Gilles

LUXonjs

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A

B

C

D

E

A

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E

Layer Stack Legend

Layer	Thickness	Type	Gerber	Df	Dk
Top Overlay		Legend	GTO		
Top Solder	0.00in	Solder Mask	GTS		3.5
Top Layer	0.00in	Signal	GTL		
	0.00in	<i>Dielectric</i>			4.3
MidLayer 1	0.00in	Internal Plane	GP1		
	0.05in	<i>Dielectric</i>			4.3
MidLayer 2	0.00in	Signal	G1		
	0.00in	<i>Dielectric</i>			4.3
Bottom Layer	0.00in	Signal	GBL		
Bottom Solder	0.00in	Solder Mask	GBS		3.5
Bottom Overlay		Legend	GBO		
Total thickness: 0.06in					

Drill Table

Symbol	Count	Hole Size	Plated	Hole Tolerance
○	65	0.01in	Plated	None
□	4	0.09in	Non-Plated	None
	69 Total			

Title: **BG0250TG**

Number: D0000999 Revision: R0M0
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1

1

ALL DIFFERENTIAL PAIRS ARE 100 OHM (+/-10%)

2

2

Transmission Line Structure Table


Transmission Line	Target Impedance	Calculated Impedance	Trace layer	Lower Trace Width	Upper Trace Width	Gap	Reference layers	Substack
Edge-Coupled Coated Microstrip	100	103.60	Top Layer	0.10mm	0.10mm	0.30mm	MidLayer 1	Board Layer Stack
Edge-Coupled Coated Microstrip	100	103.60	Bottom Layer	0.10mm	0.10mm	0.30mm	MidLayer 2	Board Layer Stack

3

3

4

4

Title: BG0250TG		
Number: D0000999	Revision: R0M0 E0	
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